

tentative

Туре	Ag <sup>*</sup> Aİ <sup>*</sup>	V <sub>DRM</sub> / V <sub>RRM</sub>	V <sub>DSM</sub> /V <sub>RSM</sub> [∨]	<b>/<sub>Т(AV)</sub></b> [A]	Chip Size [mm] x [mm]	Package Options	• <del> </del>
CWP 69-	22 🗸 🗸	2200	2300	141	13.40 13.4	sawn on foil vmnsawn wafer vm in waffle pack vm	
	*Frontside options					*Please contact IXYS chip sales	

## **Mechanical Parameters**

Area active Area total Wafer size Ø Thickness Material Max. possible chips per wafer Passivation front side Metallization top side top side Recom. wire bonds (AI) \* = Stitchbonds Number / Ø [µm] Metallization backside Reject Ink Dot Size Recom. Storage Environment sawn on foil unsawn wafer in waffle pack

cm<sup>2</sup> 1.07 1.80 cm<sup>2</sup> 150 mm 460 μm Si 76 Glassivation solderable: Ti / Ni / Ag \* bondable: ΑI Cathode Gate 16\* / 500 1 / 500 solderable (only): Ti / Ni / Ag \* Ø 0.4-1.0 mm < 6 month

### **Features**

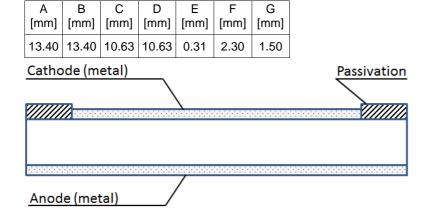
- planar design (non-mesa)
- ultra rugged for easy assembly (flat backside)
- excellent long term stability
- very low leakage current
- very low forward voltage drop

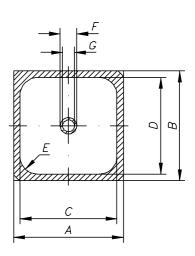
### **Applications**

- DC motor control
- AC power control
- Softstrart AC motor controller
- Light, heat and temperature control
- Solid state relays
- Controlled rectifier circuits

# \*Sinterable top/bottom side on request

#### **Dimensions**





tentative

			Ratings		
Symbol	Conditions	min.	typ.	max.	
l <sub>R</sub>	$V_D = Vr = Vrr$ Vd=Vr=1250V	••		0.3 20	
V <sub>7</sub>	I <sub>T</sub> =300 A	$T_{VJ} = 25 ^{\circ}\text{C}$ $T_{VJ} = 150 ^{\circ}\text{C}$	A	1.55 1.66	
V <sub>70</sub>	For power-loss	s calculations only		0.98	
,	T <sub>v,j</sub> = 150 °C			2.30	n
<b>V</b> <sub>G7</sub>	$V_D = 6 V$	$T_{vJ} = 25^{\circ}C$	10	1.5	
		$T_{VJ} = -40$ °C		1.6	
GT	=	$T_{VJ} = 25^{\circ}C$ 30 $T_{VJ} = -40^{\circ}C$		100 200	
V <sub>GD</sub>	T <sub>v,i</sub> = 150 °C			0.25	
GD GD	••	E-NIII		10	r
<u>.                                    </u>	t <sub>p</sub> =30 μs	$T_{VJ} = 25^{\circ}C$ $I_{G} = 0.45 \text{ A}$ $di_{G}/dt = 0.45 \text{ A}/\mu\text{s}$		200	r
l <sub>H</sub>	R <sub>GK</sub> = ∞	$T_{VJ} = 25^{\circ}C$ $V_{D} = 6 \text{ V}$		150	r
t <sub>gd</sub>	$V_D = \frac{1}{2} V_{DRM}$	$T_{VI} = 25$ °C		2	
		di <sub>G</sub> /dt =0.5 A/µ			
t <sub>q</sub>	••	$I_T = 165 \text{ A}$ -di/dt = 10 A/µs $dv/dt = 20 \text{ V/µs}$ $V_D = \frac{2}{3} \text{ Vdrm}$ $T_{VJ} = 125 ^{\circ}\text{C}$		185	
di/dt) <sub>c</sub> ,	repetitive	I <sub>T</sub> = 250 A		150	A
( <del>) G</del>	non repetitive	·		500	
		$T_{VJ} = 150 ^{\circ}\text{C}$ $di_{G}/dt = 0.45 \text{A/}\mu\text{s}$			
	$I_{G} = 0.45 \text{ A}$	$t_p = 200 \ \mu s$ $f = 50 \ Hz$			
(dv/dt) <sub>cr</sub>	T <sub>vJ</sub> = 150 °C R <sub>GK</sub> = ∞	$V_{DR} = \frac{2}{3} V_{DRM}$ method 1 (linear voltage rise)		1000	V/
P <sub>GM</sub>	T <sub>v,i</sub> = 150 °C	t <sub>o</sub> = 30 µs		10	
		$t_p = 3E \mu s$		5	
P <sub>GAV</sub>				0.5	
V <sub>RGM</sub>				10	
T <sub>VJ</sub>		-40		150	•
I <sub>T(AV)</sub> *	$T_{\rm C} = 100 ^{\circ} \text{C}$	180° rect.		141	
	$T_{VJ} = {}^{\circ}C$	180° sine		133	
I <sub>TSM</sub> *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		1700	
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		1800	
	T <sub>vJ</sub> = 150 °C	t = 10 ms (50) Hz, sine		1480	
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		1600	
Pt *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		14450	Α
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		13446	Α
	T <sub>VJ</sub> = 150 °C	t = 10 ms (50) Hz, sine		10952	Α
	$V_R = 0 V$	t = 8.3  ms  (60)  Hz,  sine		10624	Α

<sup>\*</sup> Data according to assembled product MCC 94

Data according to IEC 60747

tentative

#### **Terms of Conditions and Usage**

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you. Due to technical requirements our product may contain dangerous substances. For any information on the types in question please contact the sales office/partner, which is responsible for you.

Should you intend to use the product in aviation applications, in health or life endangering or life support applications, please notify. For any such applications we urgently recommend

- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.